

### **REMARKS**

Claims 24-35 remain in the application for consideration of the Examiner.

Reconsideration and withdrawal of the outstanding rejections are respectfully requested in light of the above amendments and following remarks.

Claims 24-35 were rejected under 35 U.S.C. § 112, first paragraph, as failing to comply with the written description requirement.

The Examiner alleges that the protective coated wafer and the lid are inconsistent with the specification because the protective material is removed before the lid is adhered.

This appears to require that the removal of the protective coating be claimed.

In this connection, Applicants respectfully traverse the requirement of the Examiner and suggest there is nothing inconsistent with the presently claimed invention.

Claims 24-35 were rejected under 35 U.S.C. § 112, second paragraph, as being indefinite.

This rejection is traversed.

The Examiner alleges that Claim 24 claims a wafer with a plurality of semiconductor chips with micromechanical components, solder encapsulation, and a lid, and Applicants appear to be claiming an intermediate product and a finished product.

However, there is nothing in the statute to prevent this presuming that the allegations of the Examiner were true.

Consequently, Applicants respectfully submit that Claims 24-35 are in full compliance with 35 U.S.C. § 112, second paragraph.

Turning now to the art rejections, Claims 24, 27, 28, 31, 34, and 35 were rejected under 35 U.S.C. § 103 as being unpatentable over Najafi in view of Karpman; Claims 25, 26, 29, 30, and 33 were rejected under 35 U.S.C. § 103 as being unpatentable over Najafi in view of Karpman and further in view of Fisher; and Claim 32 was rejected under 35 U.S.C. § 103 as being unpatentable over Najafi in view of Karpman and Shiobara.

It is respectfully submitted that Najafi does not disclose or suggest the presently claimed invention including the entire wafer surface including the micromechanical components being coated with a protective material.

Najafi is silent as to this aspect.

Whether or not Karpman discloses a wafer, including a plurality of MEM chips and whether or not one of ordinary skill in the art would consider modifying Najafi is of no moment since the resulting construction would still in no way disclose or suggest the presently claimed invention.

Whether or not Fisher discloses a digital micromirror device and one of ordinary skill in the art would consider modifying Najafi is of no moment since the resulting construction would still in no way disclose or suggest the presently claimed invention.

Additionally, whether or not Shiobara discloses silica and anhydrides and whether one of ordinary skill in the art would consider modifying Najafi is of no moment

since the resulting construction would still in no way disclose or suggest the presently claimed invention.

Karpman does not cure the above noted defects.

In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant response places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



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